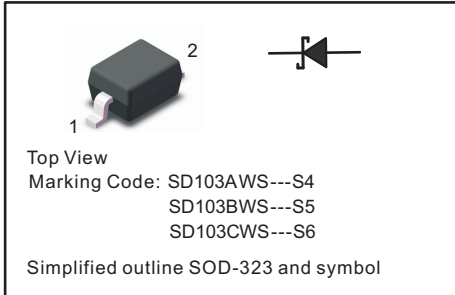


Schottky Barrier Diode

PINNING

| PIN | DESCRIPTION |
|-----|-------------|
| 1 | Cathode |
| 2 | Anode |



FEATURES

- ◆ Low Forward Voltage Drop
- ◆ Guard Ring Construction for Transient Protection
- ◆ Negligible Reverse Recovery Time
- ◆ Low Capacitance

MECHANICAL DATA

- ◆ Case: SOD-323
- ◆ Terminals: Solderable per MIL-STD-750, Method 2026
- ◆ Approx. Weight: 5.48mg / 0.00019oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

| Parameter | Symbols | SD103AWS | SD103BWS | SD103CWS | Units |
|---|-----------------|-------------------------------|----------------|-------------|---------|
| Peak Repetitive Reverse Voltage | V_{RRM} | 40 | 30 | 20 | V |
| RMS reverse voltage | V_{RMS} | 28 | 21 | 14 | V |
| Working Peak Reverse Voltage | V_{DC} | 40 | 30 | 20 | V |
| Peak Forward Surge Current, 8.3ms single half sine-wave superimposed on rated load (JEDEC method) | I_{FSM} | 13 | | | A |
| Maximum Instantaneous Forward Voltage $I_F=20mA$ $I_F=200mA$ | V_F | 0.37 0.60 | | | V |
| Power Dissipation | P_D | 200 | | | mW |
| Reverse current SD103AWS, $V_R=30V$ SD103BWS, $V_R=20V$ SD103CWS, $V_R=10V$ | I_R | 5 – – | – 5 – | – – 5 | μA |
| Thermal Resistance, Junction to Ambient Air | $R_{\theta JA}$ | 300 | | | °C/W |
| Reverse voltage $I_R=100\mu A$ | $V_{(BR)R}$ | SD103AW SD103BW SD103CW | 40 30 20 | | V |
| Reverse recovery time $I_F=I_R=200mA, I_{rr}=0.1 \times I_R, R_L=100\Omega$ | t_{rr} | 10 | | | ns |
| Forward Continuons Current | I_{FM} | 350 | | | mA |
| Total capacitance $V_R=0V, f=1MHz$ | C_{tot} | 50 | | | pF |
| Junction temperature | T_j | 125 | | | °C |
| Storage temperature | T_{stg} | -55 ~ +150 | | | °C |

Fig.1 Power Derating Curve

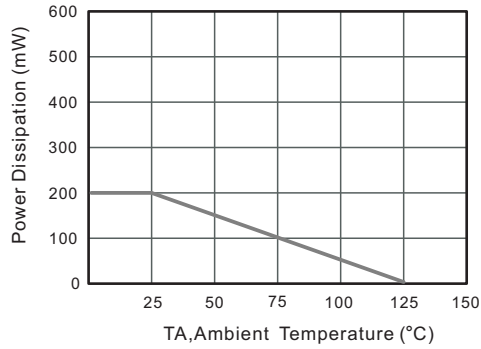


Fig.2 Typical Reverse Characteristics

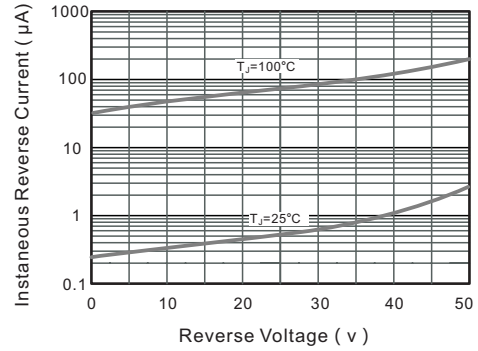


Fig.3 Forward Characteristics

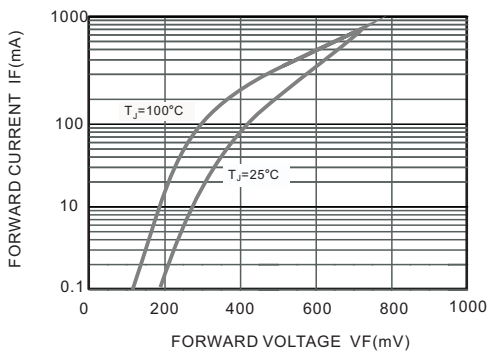


Fig.4 Maximum Non-Repetitive Peak Forward Surge Current

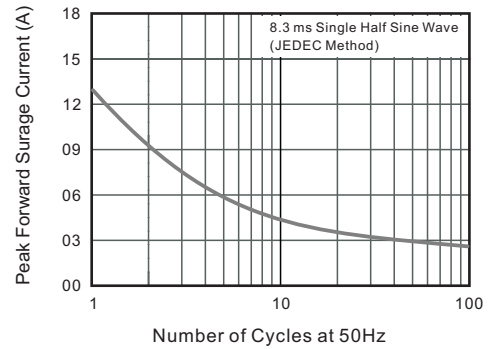


Fig.5 Typical Junction Capacitance

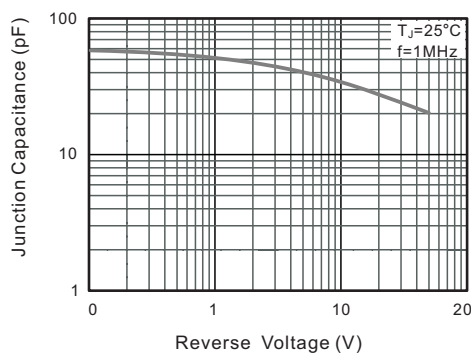
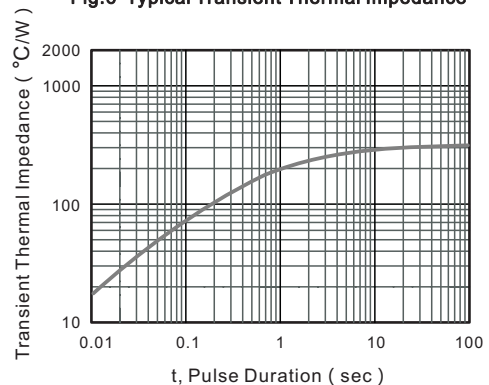


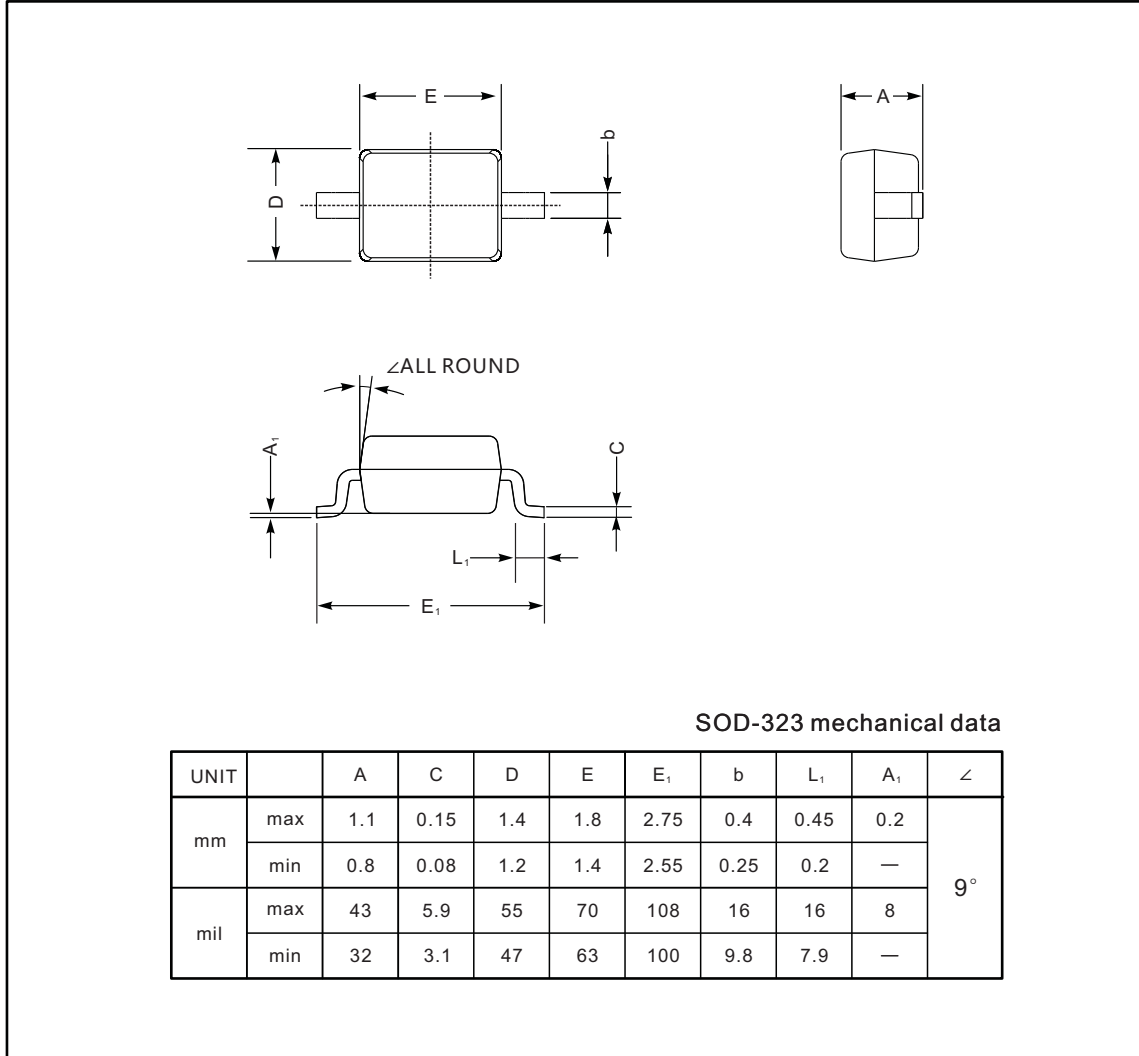
Fig.6 Typical Transient Thermal Impedance



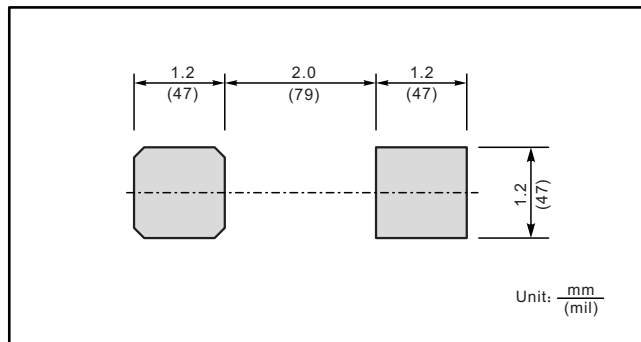
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-323



The recommended mounting pad size



单击下面可查看定价，库存，交付和生命周期等信息

[>>TWGMC\(台湾迪嘉\)](#)